

ABSTRACT OF THE DISCLOSURE

A polishing apparatus is used for polishing a workpiece such as a semiconductor wafer to a flat mirror finish. The polishing apparatus comprises a turntable
5 having a polishing surface, a top ring for holding a workpiece and pressing the workpiece against the polishing surface, a holding surface of the top ring for holding the workpiece, and a retainer ring for retaining the workpiece within the holding surface of the top ring. The holding
10 surface is deformable by fluid having variable pressure, and the retainer ring presses the polishing surface under a variable pressing force.

This Sheet Has Been Replaced
